

Electronic Patent Application Fee Transmittal

Application Number:	
Filing Date:	
Title of Invention:	SEALANT EPOXY-RESIN MOLDING MATERIAL, AND ELECTRONIC COMPONENT DEVICE
First Named Inventor:	Seichi Akagi
Filer:	Joerg-Uwe V. Szipl
Attorney Docket Number:	MIYOSH0008

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200

Pages:

Claims:

Claims in excess of 20	1615	6	50	300
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Miscellaneous-Filing:

Petition:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1200